

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2	"20050046003"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/26 21:31
L2	592819	(stack stacking stacked stackable mount mounting mounted mountable) with (semiconductor die chip ic (integrated adj circuit) component dice)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/26 22:18
L3	769677	(opening via hole gap space) with (carrier board substrate pcb ((printed wiring circuit) adj3 board))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/26 21:35
L4	2	1 and 2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/26 21:35
L5	108403	3 and 2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/26 21:36
L6	191177	(encapsulation encapsulated encapsulating encasulate encase resin epoxy encapsulant) with (exposing expose exposed open opening cavity)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/26 22:22
L7	24842	6 and (heat with (dissipate dissipating dissipation dissipated sink radiate radiating radiated metal thermal block blocking))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/26 22:22
L8	46816	2 same 3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/26 21:40

L9	1508	6 same 8	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/26 21:41
L10	145	9 same (heat with (dissipate dissipating dissipation dissipated sink radiate radiating radiated metal thermal block blocking))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/26 22:07
L11	1363	9 not 10	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/26 22:07
L12	579543	(stack stacking stacked stackable mount mounting mounted mountable) with (diode led semiconductor die chip ic (integrated adj circuit) component dice)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/26 22:19
L13	46816	2 same 3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/26 22:19
L14	3911	13 same (heat with (dissipate dissipating dissipation dissipated sink radiate radiating radiated metal thermal block blocking))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/26 22:19
L15	145	14 same 6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/26 22:21
L16	0	15 not 10	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/26 22:21

L17	21080	12 and 6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/26 22:22
L18	9766	3 and 17	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/26 22:22
L19	3864	18 and (heat with (dissipate dissipating dissipation dissipated sink radiate radiating radiated metal thermal block blocking))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/26 22:23
L20	3531	19 not 11	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/26 22:23
L21	2628	wire and 20	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/26 22:23
L22	314	lens and 21	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/26 22:24
L23	1	"6521881".PN.	USPAT; USOCR	OR	OFF	2005/06/26 22:40
L24	1	"6680525".PN.	USPAT; USOCR	OR	OFF	2005/06/26 22:40
L25	1	"20020173071".PN.	US-PGPUB	OR	OFF	2005/06/26 22:41
L26	1	"6590269".PN.	USPAT; USOCR	OR	OFF	2005/06/26 22:41
L27	1	"6531341".PN.	USPAT; USOCR	OR	OFF	2005/06/26 22:41
L28	1	"6455774".PN.	USPAT; USOCR	OR	OFF	2005/06/26 22:41
L29	1	"6396116".PN.	USPAT; USOCR	OR	OFF	2005/06/26 22:42